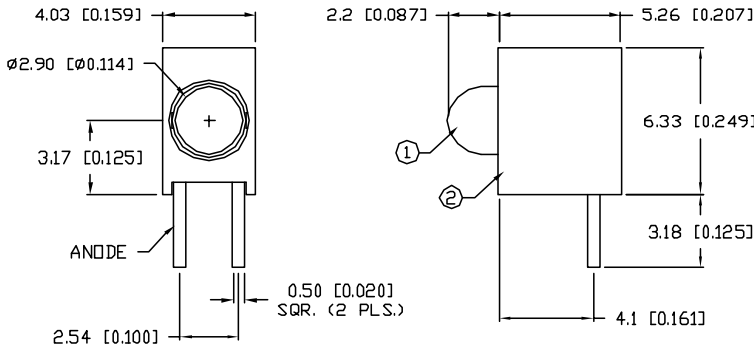


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PART NUMBER
SSF-LXH303LID

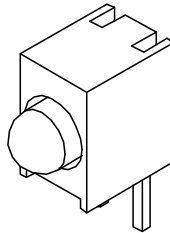
REV.
E

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	REDRAWN.	12.6.93
B	REMOVED MAX FROM DIMS.	12.16.93
C	UPDATED SAFE OPER. SPECS.	10.12.94
D	E.C.N. #10BRDR. & REDRAWN.	9.2.98
E	E.C.N. #10675.	10.30.00



NOTES:

1. SSL-LX3044LID, LOW CURRENT RED LED.
2. SSH-LXH303, BLACK NYLON HOLDER, UL 94V-0.
3. PARTS NEED TO BE PACKED IN ANTI-STATIC TUBES.



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		40		mcd	$I_f=20\text{mA}$
	1.0			mcd	$I_f=2\text{mA}$
VIEWING ANGLE		60		$2x$ theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.6	$\text{mW}/^{\circ}\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^{\circ}\text{C}$
SOLDERING TEMP.	+260	$^{\circ}\text{C}$
2.0mm FROM BODY		3 SEC. MAX
* $t < 10\mu\text{s}$		

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= ±0.00 DECIMAL PRECISION MAX.= ±0.00 DECIMAL PRECISION

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REV.	PART NUMBER	CONFIDENTIAL INFORMATION	LUMEX INCORPORATED	290 E. HELLEN ROAD PALATINE, ILLINOIS 60067 PHONE: (847) 359-2790 WEB: http://www.lumex.com
E	SSF-LXH303LID	THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	LUMEX INCORPORATED	
T-3mm (T-1) LED FAULT INDICATOR, 635nm RED LED, RED DIFFUSED LENS, LOW CURRENT.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: BC	CHECKED BY: APPROVED BY: DATE: 1.31.91 PAGE: 1 OF 1 SCALE: N/A